# LNJ3W0C83RA

### Hight Bright Surface Mounting Chip LED

#### Wide Angle Type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	55	mW	
Forward current	I <sub>F</sub>	20	mA	
Pulse forward current *	I <sub>FP</sub>	60	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

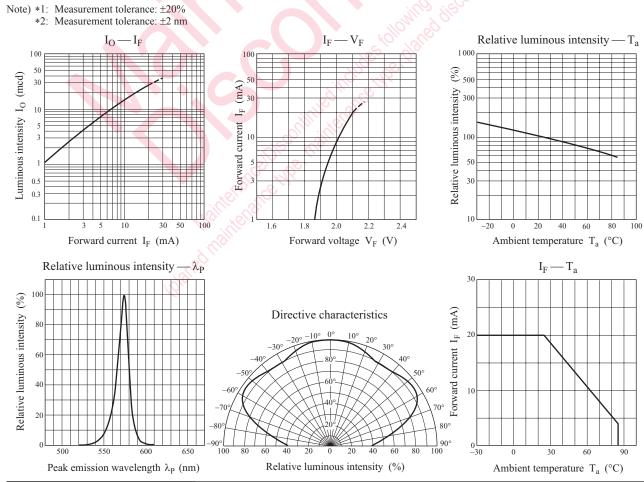
Lighting Color

• Yellow Green

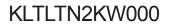
Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

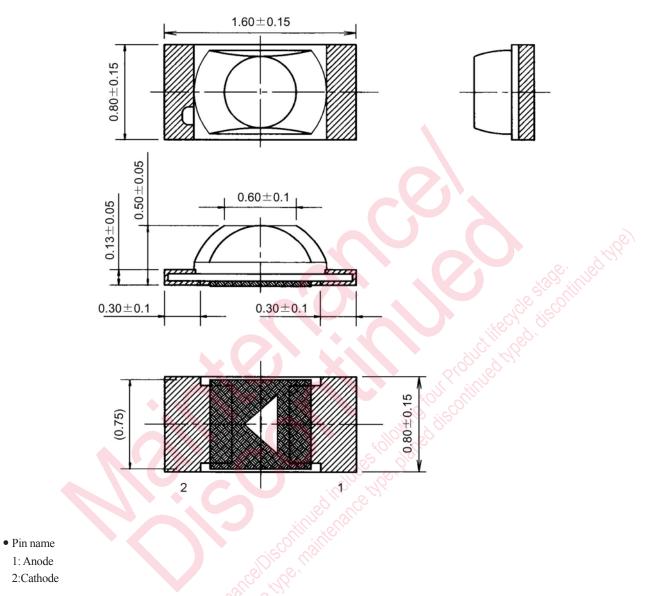
#### Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

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Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	Io	$I_F = 5 \text{ mA}$	3.2	7.5 🧹		mcd
Reverse current	I <sub>R</sub>	$V_R = 4 V$		200	100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 5 \text{ mA}$		1.95	2.30	V
Peak emission wavelength	$\lambda_{\mathrm{P}}$	$I_F = 5 \text{ mA}$		575		nm
Dominant emission wavelength *2	$\lambda_d$	$I_F = 5 \text{ mA}$	566	572	575	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$	1 all	15		nm
Viewing angle	20 <sub>1/2</sub>	$I_F = 5 \text{ mA}$	U <sub>fli</sub>	165		0



Package (Unit: mm)





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